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(71) Applicant: Samsung Display Co., Ltd., Yongin-si

Inventors: **HUN-TAE KIM**, Seoul (KR);

GYUMDONG BAE, Cheonan-si (KR); DONGHO YOON, Anyang-si (KR)

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(57)**ABSTRACT**

A release film on a printed circuit board and a connector connected to the printed circuit board includes a first release film disposed on a first surface of the printed circuit board and a surface of the connector, a second release film disposed on a second surface of the printed circuit board opposite to the first surface of the printed circuit board, and a first adhesive attached to a portion of a surface of the first release film that does not overlap the second release film, extending towards the second release film and covering a portion of a surface of the second release film that does not face the first release film.

